



#8/Amoldt B
5.6.03
C. Moore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Yoshihiro TAKAHASHI et al.

Serial No.: 09/986,096

Group Art Unit: 2817

Filed: November 7, 2001

Examiner: Summons, Barbara

Atty. Docket No. 2000P342686

For: SAW FILTER DEVICE AND PACKAGE FOR ACCOMMODATING THE SAME

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231

AMENDMENT UNDER 37 C.F.R. 1.111

Sir:

In response to the Office Action dated February 6, 2003, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please replace the paragraph, beginning on page 3, line 27 and continuing to page 4, line 10, with the following:

B¹

A plastic package may be used to reduce the cost of the SAW filter. However, it is difficult to form a metal film by plating or deposition on the plastic package. That is, it is difficult to provide, on the package, a means for permitting escape of charge generated due to polarization. It is therefore inevitable, as shown in Fig. 14, that the SAW filter be packaged without presence of any metal film between plastic package 7 and SAW filter 100. In order that the plastic package 7 can be used, it is important that the structure of the chip substrate of the SAW filter 100 is free from polarization or capable of permitting escape of charge generated due to polarization.

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